

Chipsmall Limited consists of a professional team with an average of over 10 year of expertise in the distribution of electronic components. Based in Hongkong, we have already established firm and mutual-benefit business relationships with customers from, Europe, America and south Asia, supplying obsolete and hard-to-find components to meet their specific needs.

With the principle of "Quality Parts, Customers Priority, Honest Operation, and Considerate Service", our business mainly focus on the distribution of electronic components. Line cards we deal with include Microchip, ALPS, ROHM, Xilinx, Pulse, ON, Everlight and Freescale. Main products comprise IC, Modules, Potentiometer, IC Socket, Relay, Connector. Our parts cover such applications as commercial, industrial, and automotives areas.

We are looking forward to setting up business relationship with you and hope to provide you with the best service and solution. Let us make a better world for our industry!



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FEP16AT - FEP16JT

PIN 1 O CASE PIN 2 Positive CT

Features

- · Low forward voltage drop.
- · High surge current capacity.
- High current capability.
- · High reliability.

• Average Forward Current Rating at 16A (8A per Diode).

PIN 1 OPIN 3 OPIN 1 OPI

Fast Rectifiers (Glass Passivated)

Absolute Maximum Ratings* T_A = 25°C unless otherwise noted

Symbol	Parameter	Value								Units
		16AT	16BT	16CT	16DT	16FT	16GT	16HT	16JT	1
V_{RRM}	Maximum Repetitive Reverse Voltage	50	100	150	200	300	400	500	600	V
I _{F(AV)}	Average Rectified Forward Current, .375 " lead length @ T _A = 100°C	· I			Α					
I _{FSM}	Non-repetitive Peak Forward Surge Current 8.3 ms Single Half-Sine-Wave	200			А					
T _{sta}	Storage Temperature Range	e -55 to +150			°C					
T_J	Operating Junction Temperature	-55 to +150			°C					

^{*}These ratings are limiting values above which the serviceability of any semiconductor device may be impaired.

Thermal Characteristics

Symbol	Parameter	Value	Units	
P_{D}	Power Dissipation	8.33	W	
$R_{\theta JA}$	Thermal Resistance, Junction to Ambient	15	°C/W	
$R_{\theta JL}$	Thermal Resistance, Junction to Lead	2.2	°C/W	

Electrical Characteristics T_A = 25°C unless otherwise noted

Symbol	Parameter	Device							Units
		16AT	16BT	16CT	16DT	16FT	16GT	16HT	16JT
V _F	Forward Voltage @ 8.0A	0.95		1.3		1.5		V	
t _{rr}	Reverse Recovery Time $I_F = 0.5 \text{ A}, I_R = 1.0 \text{ A}, I_{RR} = 0.25 \text{ A}$	35				50			ns
I _R	Reverse Current @ rated V_R $T_A = 25^{\circ}C$ $T_A = 100^{\circ}C$	10 500				μ Α μ Α			
Ст	Total Capacitance $V_R = 4.0$. f = 1.0 MHz	85 60			0	pF			

Typical Characteristics

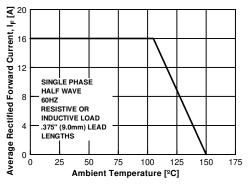


Figure 1. Forward Current Derating Curve

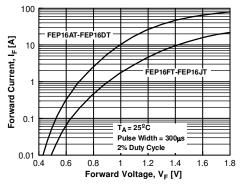


Figure 3. Forward Voltage Characteristics

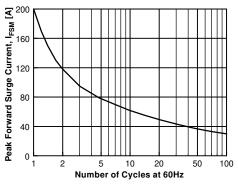


Figure 2. Non-Repetitive Surge Current Reverse Characteristics

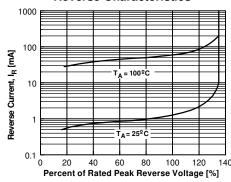


Figure 4. Reverse Current vs Reverse Voltage

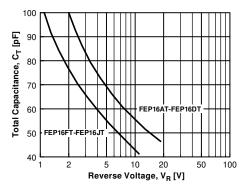
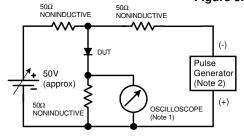
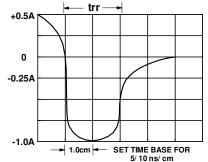


Figure 5. Total Capacitance





Reverse Recovery Time Characterstic and Test Circuit Diagram

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Definition of Terms

Datasheet Identification	Product Status	Definition				
Advance Information	Formative or In Design	This datasheet contains the design specifications for product development. Specifications may change in any manner without notice.				
Preliminary	First Production	This datasheet contains preliminary data, and supplementary data will be published at a later date. Fairchild Semiconductor reserves the right to make changes at any time without notice in order to improve design.				
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Rev. H4